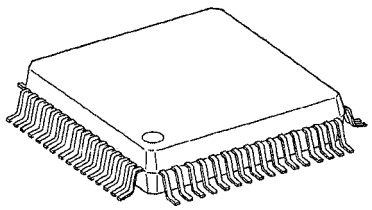
TOSHIBA CMOS DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

TMPN3150B1AFG

Neuron ® Chip
For Distributed Intelligent Control Networks (LONWORKS®)

The TMPN3150B1AFG is a Neuron Chip which configures LONWORKS nodes in combination with external memory.
Neuron Chips have all the built-in communications and control functions required to implement LONWORKS nodes. These nodes may then be easily integrated into highly-reliable distributed intelligent control networks.
The typical functions for this chip are explained below.



QFP64-P-1414-0.80C

Weight : 1.0g (Typ.)

FEATURES

- I / O Functions
  - Eleven programmable I / O pins.
  - Two programmable 16-bit timers and counters built in.
  - 34 different types of I / O functions to handle a wide range of input and output.
  - ROM firmware image containing pre-programmed I / O drivers, greatly simplifying application programs.
    (Stored in external ROM)
- Network functions
  - Two CPUs for communication protocol processing built in.
    The communications and application CPUs execute in parallel.
  - Equipped with a built-in LonTalk protocol which supports all seven levels of the OSI reference model with ISO.
  - Highly reliable communication protocol is supplied as firmware.
  - Built-in twisted-pair wire transceiver
  - Equipped with communications modes and communication speeds which support various types of external transceivers.
    Supports twisted-pair wire, power line, radio (RF), infrared, coaxial cables and fiber optics.
  - Communication port transceiver modes and logical addresses stored within the EEPROM.
    Can be amended via the network.

- Other functions
  - Application programs are also stored within the EEPROM.
    Can be updated by downloading over the network. EEPROM can be externally added.
  - Built-in watch-dog timer.
  - Each chip has a unique ID number.
    Effective during the logical installation of networks.
  - Low electrical consumption mode supported with a sleep mode.
  - Built-in low-voltage detection circuit.
    Prevents incorrect operations and writing errors in the EEPROM during drops in power voltage.
  - The package is QFP64-P-1414-0.80C (Lead-Free Type (Pd PrePlated Frame)).

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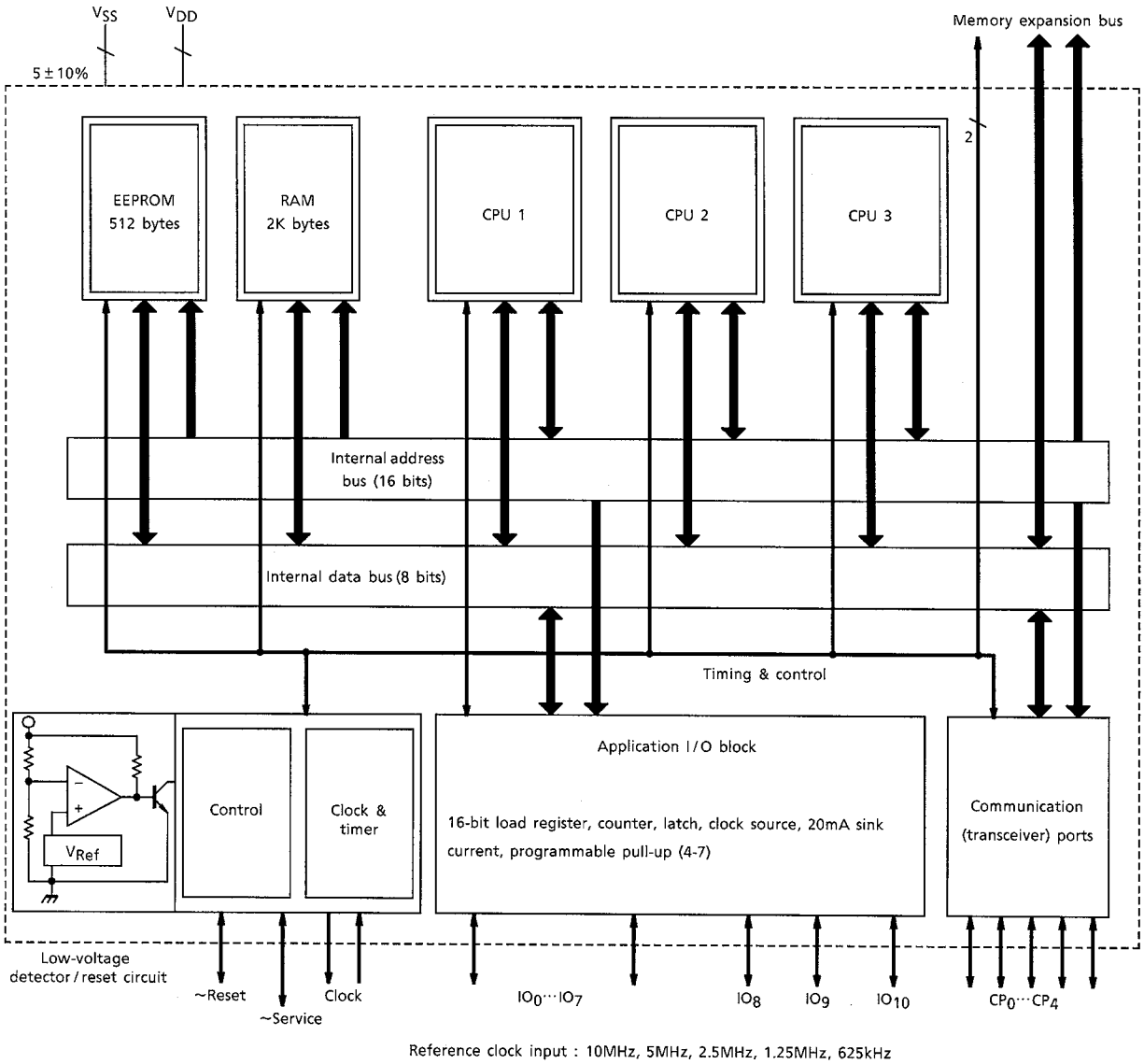
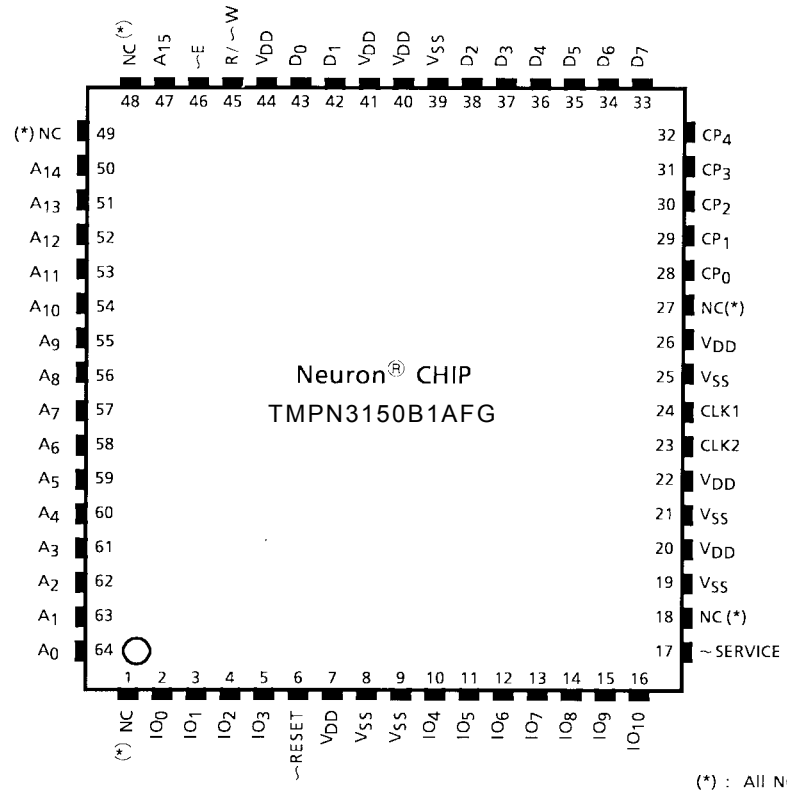
BLOCK DIAGRAM



Reference clock input : 10MHz, 5MHz, 2.5MHz, 1.25MHz, 625kHz

ITEM	TMPN3150B1AFG
CPU	8-bit CPU×3
RAM	2,048 bytes
ROM	—
EEPROM	512 bytes
16-bit Timer / Counter	2 channels
External Memory Interface	Available
Package	64-pin SOP

PIN ASSIGNMENT



(*) : All NC pins should be open.

PIN FUNCTION

PIN No.	PIN NAME	I / O	PIN FUNCTION
24	CLK1	Input	Oscillator connection, or external clock input.
23	CLK2	Output	Oscillator connection. Leave open when external clock is input to CLK1.
6	~RESET	I / O (built-in pull-up)	Reset pin. (Active low)
17	~SERVICE	I / O (built-in configurable pull-up)	Service pin. Indicator output during operation.
2~5	IO_0~IO_3	I / O	Large current sink capacity (20mA). General I / O port.
10~13	IO_4~IO_7	I / O (built-in configurable pull-up)	General I / O port. One of IO_4 to IO_7 can be specified as No.1 timer / counter input. Output signal can be output to IO_0. IO_4 can be used as the No.2 timer / counter input with IO_1 as output.
14~16	IO_8~IO_{10}	I / O	General I / O port. Can be used for serial communication with other device.
43, 42, 38~33	D_0, D_1, D_2~D_7	I / O	Data bus for memory expansion
45	R / ~W	Output	Output port for controlling read / write for memory expansion
46	~E	Output	Output port for controlling memory expansion
47, 50~64	A_{15}, A_{14}~A_0	Output	Address output port for memory expansion
7, 20, 22, 26, 40, 41, 44	V_{DD}	Input	Power input (5.0V Typ.)
8, 9, 19, 21, 25, 39	V_{SS}	Input	Power input (0V GND)
1, 18, 27, 48, 49	NC	—	Do not connect anything. Leave pins open.
28~32	CP_0~CP_4	I / O	Bidirectional port for communications. Supports several communications protocols by specifying mode.

* : ● The ~SERVICE and IO_4 ~ IO_7 terminals are programmable pull-ups.
● All V_{DD} terminals must be externally connected.
● All V_{SS} terminals must be externally connected.

MAXIMUM RATINGS (V_{SS} = 0V, V_{SS} typ.)

CHARACTERISTICS	SYMBOL	RATING	UNIT
Power Supply Voltage	V_{DD}	−0.3~7.0	V
Input Voltage	V_{IN}	−0.3~V_{DD}+0.3	V
Power Dissipation	PD	800	mW
Storage Temperature	T_{stg}	−65~150	°C

OPERATING CONDITIONS

ITEM	SYMBOL	MIN	TYP.	MAX	UNIT
Operating Voltage	V_{DD}	4.5	5.0	5.5	V
Input Voltage (TTL)	$V_{IH(1)}$	2.0	—	V_{DD}	V
	$V_{IL(1)}$	V_{SS}	—	0.8	V
Input Voltage (CMOS)	$V_{IH(2)}$	V_{DD}−0.8	—	V_{DD}	V
	$V_{IL(2)}$	V_{SS}	—	0.8	V
Operating Frequency	f_{osc}	0.625	—	10	MHz
Operating Temperature	T_{opr}	−40	—	85	°C

ELECTRICAL CHARACTERISTICS

DC characteristic (V_{DD} = 5.0 V ± 10%, V_{SS} = 0 V, Ta = −40~85°C)
(Above operating conditions apply unless otherwise states.)

CHARACTERISTICS	SYMBOL	PINS	TEST CONDITION		MIN	MAX	UNIT
LOW Output Voltage (1)	V_{OL} (1)	IO_0~IO_3	I_{OL}=20mA		0	0.8	V
			I_{OL}=10mA		0	0.4	V
LOW Output Voltage (2)	V_{OL} (2)	~SERVICE	Duty cycle=50%	I_{OL}=20mA	0	0.8	V
				I_{OL}=10mA	0	0.4	V
LOW Output Voltage (3)	V_{OL} (3)	CP_2, CP_3	I_{OL}=40mA		0	1.0	V
LOW Output Voltage (4)	V_{OL} (4)	Others (Note 1)	I_{OL}=1.4mA		0	0.4	V
HIGH Output Voltage (1)	V_{OH} (1)	IO_0~IO_3	I_{OH}=−1.4mA		V_{DD} −0.4	V_{DD}	V
HIGH Output Voltage (2)	V_{OH} (2)	~SERVICE	I_{OH}=−1.4mA		V_{DD} −0.4	V_{DD}	V
HIGH Output Voltage (3)	V_{OH} (3)	CP_2, CP_3	I_{OH}=−40mA		V_{DD} −1.0	V_{DD}	V
HIGH Output Voltage (4)	V_{OH} (4)	Others (Note 1)	I_{OH}=−1.4mA		V_{DD} −0.4	V_{DD}	V
Input Current	I_{IN}	(Note 2)	V_{IN}=V_{SS}~V_{DD}		−10	+10	μA
Pull-up Current	I_{PU}	IO_4~IO_7 ~SERVICE, ~RESET (Note 3)	V_{IN}=0V		−30	−300	μA
Low-voltage Detection Level	V_{LVD}	V_{DD}	—		3.8	4.5	V

Note1 : Output voltage characteristics exclude the ~RESET pin and CLK2 pin.
Note2 : Excludes pull-up input pins.
Note3 : The IO_4 to IO_7 and ~SERVICE pins have programmable pull-ups. ~RESET has a fixed pull-up.

ITEM		SYMBOL	TYP.	MAX	UNIT
Operating Mode Current Consumption	10 MHz Clock	$I_{DD\ (OP)}$	18	30	mA
	5 MHz Clock		10	15	
	2.5 MHz Clock		5	8	
	1.25 MHz Clock		2.5	5	
	0.625 MHz Clock		1.5	3	
Sleep Mode Current Consumption		$I_{DD\ (SLP)}$	18	100	μA

Note: Test conditions for current dissipation

V_{DD}=5V, all output=with no load, all input=0.2V or below or V_{DD}−0.2V, programmable pull-up=off, crystal oscillator clock input, differential receiver disabled.

The current value (typ.) is a typical value when Ta=25°C.

The current value (max) applies to the rated temperature range at V_{DD}=5.5V.

200μA (typ.) to 600μA (max) is added to the current of the differential receiver when the receiver is enabled.

The differential receiver is enabled by either of the following conditions :

- When the Neuron chip is in Run mode and the communication ports are in Differential mode.
- When the Neuron chip is in Sleep mode, the communication ports are in Differential mode, and the Comm Port Wakeup is not masked.

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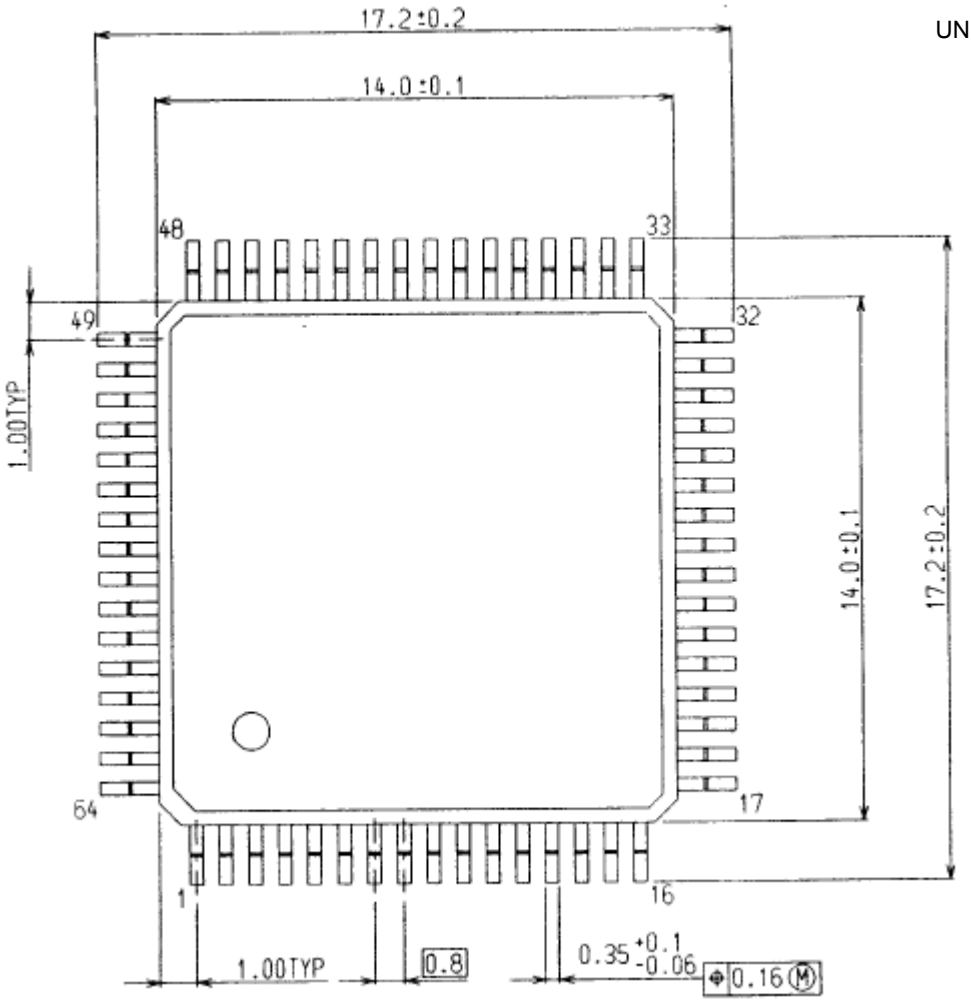
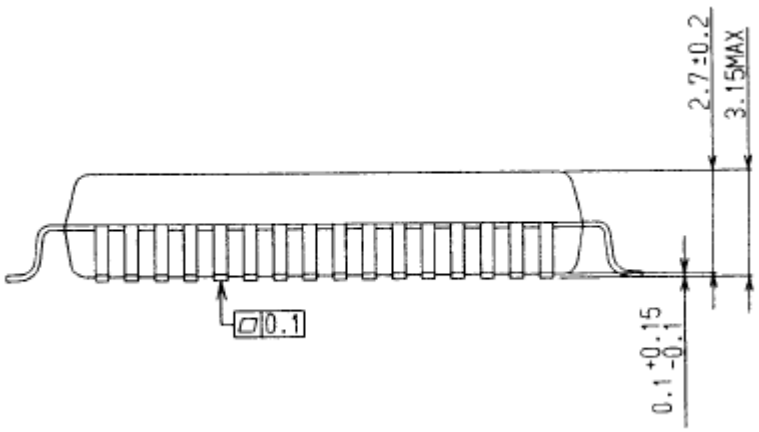
PACKAGE DIMENSONS

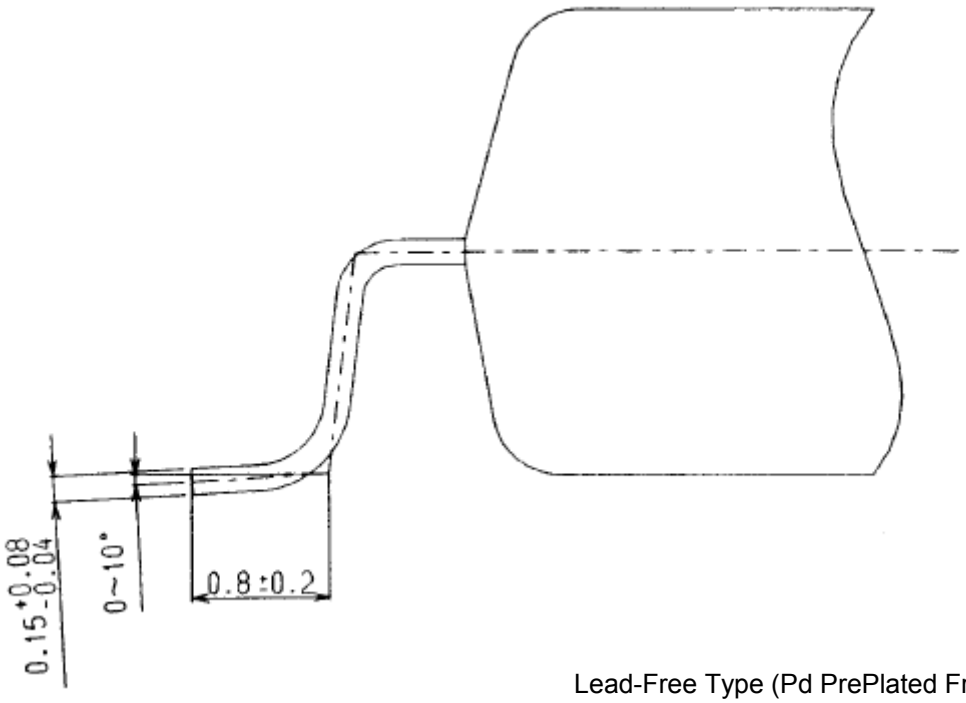
QFP64-P-1414-0.80C

UNIT: mm





UNIT: mm



Lead-Free Type (Pd PrePlated Frame)